ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						ials and Mf	g Inforn	nation			
Supplier Inform	ation															
Company name*			Company unique ID			ī	Unique ID Authority					Response Date*				
onsemi												2025-06-06				
Contact Name			Title - Contact]	Phone - Contact*					Email - Contact*				
Product-Env-Stewa	rds		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
authorized Represei	ntative*	Title - Representative]	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Requester	r Item Number Mfr Item		em Number Mfr Item Name				Effective Dat	te Versi	Version N		Manufacturing Site		Weight* UOM		OM	Unit Type
	,	74LVTH373MTCX		LV OCTAL TRANSP LATCH BH		ВН	2025-06-06	2025-06-06 PH4			73.596		mg	;	Each	
Ianufacturing l	Proccess Information															
Terminal I	l Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	SL Rating	Peak Process Body Temperatu		re Max Time at Peak Temper		Temperatu	ture Number of Reflow Cycles		es		
Precious 1 Sn)			CU Alloy 1		1		260		C		30 seco		s 3			
comments																
vel 1 - maximum ti	ime at peak temperature di	uring sold	lering is 10-3	0 seconds												
	on regarding material comp															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.25	mg	Supplier	Silicon (Si)	7440-21-3		1.25	mg
Die Attach	0.136	mg		Bismaleimide Resin	proprietary data		0.0224	mg
			Supplier	Other Additive Agents	Proprietary Data		0.0048	mg
			Supplier	Silver (Ag)	7440-22-4		0.1088	mg
Lead Frame	30.624	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0459	mg
			Supplier	Silicon (Si)	7440-21-3		0.1991	mg
			В	Nickel (Ni)	7440-02-0		0.9187	mg
			Supplier	Copper (Cu)	7440-50-8		29.4603	mg
Mold Compound-Black	40.867	mg		Epoxy resin	proprietary data		3.8824	mg
			Supplier	Phenol Resin	Proprietary Data		2.0433	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2043	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.7369	mg
Plating	0.223		Supplier	Palladium (Pd)	7440-05-3		0.006	mg
			В	Nickel (Ni)	7440-02-0		0.213	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg
Wire Bond - Au	0.496	mg	Supplier	Gold (Au)	7440-57-5		0.496	mg